


















# Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.40mil	3.5
4		Top Layer	Copper	1.40mil	
5		Dielectric 1	FR-4	19.68mil	4.8
6		Ground	Copper	1.42mil	
7		Dielectric 7		5.00mil	4.2
8		Signal Layer 2	Copper	1.42mil	
9		Dielectric 6		10.00mil	4.2
10		Signal Layer 1	Copper	1.42mil	
11		Dielectric 4		5.00mil	4.2
12		Power	Copper	1.42mil	
13		Dielectric 8		10.00mil	4.2
14		Bottom Layer	Copper	1.40mil	
15		Bottom Solder	Solder Resist	0.40mil	3.5
16		Bottom Overlay			
17		Bottom Paste			
	Height : 58.95mil				